DERWENT-ACC-NO: 1993-348008

DERWENT-WEEK: 199344

TITLE: Mould-release material useful for patterning prepd.
bonding emboss processed polyolefin resin film to support
using radiation curable resin

INVENTOR: HARADA J; KATO T

PATENT-ASSIGNEE: MITSUBISHI PAPER MILLS LTD[MITY]

PRIORITY-DATA: 1992JP-051934 (March 10, 1992)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
JP 05254066 A	October 5, 1993	JA

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 05254066A	N/A	1992JP-051934	March 10, 1992

INT-CL-CURRENT:

TYPE	IPC	DATE
CIPP	B29C33/68	20060101
CIPS	B29C59/00	20060101
CIPS	B32B27/08	20060101
CIPS	B32B27/10	20060101
CIPS	B32B27/32	20060101
CIPN	B29K105/24	20060101
CIPN	B29K23/00	20060101

ABSTRACTED-PUB-NO: JP 05254066 A

BASIC-ABSTRACT:

The material is prepd. by bonding polyolefin resin film emboss-processed to
support not emboss-processed, using a radiation curable resin polymerised by
irradiation of UV rays or electron beams.

Pref. the polyolefin resin film is crosslinked by irradiation of electron
beams. The radiation curable resin has an **acryloyl** gp. and has a structure of
epoxy gps. isocyanates, and/or urethane linkages. In the prodn. (claimed), a
polyolefin resin film is emboss-processed. One or both of support and the
emboss-processed polyolefin resin film are coated with radiation curable resin.
The resin film and the support are contacted closely with each other. The
radiation curable residue is cured by irradiation of UV rays or electron beams.

USE/ADVANTAGE - For prodn. of **synthetic leather** C fibre prepregs, floorings,
marking films, etc. This material has good patterning property, pattern-durability, repeated use property etc.

TITLE-TERMS: MOULD RELEASE MATERIAL USEFUL PATTERN PREPARATION BOND EMBOSS
PROCESS POLYOLEFIN RESIN FILM SUPPORT RADIATE CURE

DERWENT-CLASS: A17 A35 P73

CPI-CODES: A04-G01C; A08-R03A; A11-C01D; A11-C02B; A12-B02B; A12-R03;
A12-S06B; A12-S08C;

UNLINKED-DERWENT-REGISTRY-NUMBERS: 5086U

ENHANCED-POLYMER-INDEXING:
Polymer Index [1.1]
017 ; G0033*R G0022 D01 D02 D51 D53; H0000; H0011*R; S9999 S1285*R;
L9999 L2391; L9999 L2073; M9999 M2073; P1150;
Polymer Index [1.2]
017 ; ND07; ND01; K9698 K9676; K9574 K9483; K9814 K9803 K9790; Q9999
Q7818*R; Q9999 Q7829 Q7818; Q9999 Q9121; Q9999 Q6848 Q6826; B9999
B5276*R; N9999 N5721*R; N9999 N7192 N7023; N9999 N7147 N7034 N7023;
N9999 N7090 N7034 N7023; K9892; K9789;
Polymer Index [1.3]
017 ; N9999 N7169 N7023; B9999 B5447 B5414 B5403 B5276; K9712 K9676;
Polymer Index [1.4]

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    017 ; D00 D09 C* 4A R05086 200716;  S9999 S1070*R;  A999 A419;
Polymer Index [2.1]
    017 ; M9999 M2017;  M9999 M2062;  M9999 M2186;  M9999 M2813;
L9999
    L2391;  L9999 L2073;  M9999 M2073;  P0464*R;
Polymer Index [2.2]
    017 ; M9999 M2017;  M9999 M2062;  M9999 M2186;  M9999 M2813;
L9999
    L2391;  L9999 L2073;  M9999 M2073;  P1592*R F77;
Polymer Index [2.3]
    017 ; ND07;  ND01;  K9698 K9676;  K9574 K9483;  K9814 K9803
K9790;  Q9999
    Q7818*R;  Q9999 Q7829 Q7818;  Q9999 Q9121;  Q9999 Q6848 Q6826;
B9999
    B5276*R;  N9999 N5721*R;  N9999 N7192 N7023;  N9999 N7147 N7034
N7023;
    N9999 N7090 N7034 N7023;  K9892;  K9789;
Polymer Index [2.4]
    017 ; Q9999 Q6644*R;  Q9999 Q9154;  B9999 B4988*R B4977 B4740;
K9869
    K9847 K9790;  K9483*R;
Polymer Index [2.5]
    017 ; D00 D09 C* 4A R05086 200716;  S9999 S1070*R;  A999 A419;


POLYMER-MULTIPUNCH-CODES-AND-KEY-SERIALS:
Key Serials: 0011 0147 0150 0153 0212 0229 0231 0232 0233 1282 1294
1999 2009
2016 2020 2021 2022 2194 2198 2213 2215 2220 2437 2479 2488 2493 2513
2655 2682
2694 2726 2836 2845 3205 3206
Multipunch Codes: 03- 034 04- 041 046 08& 10- 15- 17& 17- 23& 231 246
308 309
359 38& 39& 431 435 443 446 466 468 473 477 597 613 614 654 688 722
723 03- 04-
08& 10- 15- 150 17& 17- 226 23& 231 239 246 250 308 309 353 359 38&
39& 431 443
446 473 477 58- 597 609 613 614 654 722 723 724

SECONDARY-ACC-NO:
CPI Secondary Accession Numbers:      1993-154197
Non-CPI Secondary Accession Numbers:  1993-268631
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